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#3



From: **Michael K. Skrehot**
Texas Instruments Incorporated
 Facsimile: 972-917-4417
 Phone: 972-917-5653

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Jimmy Liang**Docket Number: **TI-32508**Serial No.: **10/032,907**Art Unit: **2811**Filed: **12/28/2001**Examiner: **TBD**

For: **Method And Apparatus For Flip Chip Device**
Assembly By Radlant Heating

Conf. No.: **9018**

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at (703) 746-4060 (OIPE) on the date shown below:

Elizabeth Austin

Date

10/21/2002

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input type="checkbox"/> AMENDMENT (# Pages)
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT (# Pages)
<input checked="" type="checkbox"/> DECLARATION - COPY	<input type="checkbox"/> NOTICE OF APPEAL (# Pages)
<input checked="" type="checkbox"/> ASSIGNMENT & FORM PTO 1595 - COPY	<input type="checkbox"/> APPEAL (# Pages)
<input checked="" type="checkbox"/> FORMAL DRAWINGS (4 pages) - COPY	<input type="checkbox"/> ISSUE FEE (# Pages)
<input checked="" type="checkbox"/> LETTER TO OFFICIAL DRAFTS PERSON-COPY	<input type="checkbox"/> REPLY BRIEF (IN TRIPLICATE) (# Pages)
<input checked="" type="checkbox"/> RESPONSE TO NOTICE TO FILE MISSING PARTS - COPY	<input checked="" type="checkbox"/> RESPONSE TO REQUEST FOR SUBSTITUTE PAPERS
<input type="checkbox"/> CONTINUATION APP'N (# Pages)	<input type="checkbox"/> DIVISIONAL APP'N
	<input checked="" type="checkbox"/> COPY OF SENT AND RETURNED POST CARD
NAME OF INVENTOR(S): Jimmy Liang	RECEIPT DATE & SERIAL NO.: 10/032,907
TITLE OF INVENTION: Method And Apparatus For Flip Chip Device Assembly By Radlant heating	FILING DATE: 12/28/2001
TI FILE NO.: TI-32508 DEPOSIT ACCT. NO.: 20-0668	
DATE FAXED: October 21, 2002	
DUE: October 24, 2002	
ATTY/SEC'Y: Michael Skrehot / E. Austin	

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Texas Instruments Incorporated
 PO Box 655474, M/S 3999
 Dallas, TX 75265

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

Jimmy Liang, et al.

Docket No.: TI-32508

Art Unit: TBD

Serial No: 10/032,907

Filed: 12/28/01

For: Method and Apparatus for Flip Chip Device Assembly by Radiant Heating

Assistant Commissioner for

Patents

Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)	
I hereby certify that the above correspondence is being deposited	
with the	U.S. Postal Service on
3-11-02	as First Class Mail in an
envelope addressed to: Assistant Commissioner for Patents,	
Washington, D.C.	
<i>Karen Vertz</i>	3-11-02
Karen Vertz	Date

RESPONSE TO NOTICE TO FILE MISSING PARTS OF APPLICATION

Dear Sir:

In response to the Notice of Missing Parts dated February 22, 2002 please charge the fee of \$130.00 for the surcharge under 37 CFR 1.27 to Deposit Account No. 20-0668 of Texas Instruments Incorporated.

Please find enclosed the Declaration/Power of Attorney (1 page), an Assignment with Form PTO 1595 and formal drawings for the above-referenced case. The Commissioner is hereby authorized to charge any additional fees which may be required. **This sheet is submitted in triplicate.**

Respectfully submitted,

Gary C. Honeycutt
Gary C. Honeycutt
Attorney for Applicants
Reg. No. 20,250

Texas Instruments Incorporated
Mail Station 3999
P.O. Box 655474
Dallas, TX 75265
(214) 939-8651

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re the Application of: **Jimmy Liang**
Serial No.: **10/032,907**
Filed: **12/28/2001**
For: **Method And Apparatus For Flip Chip Device**
Assembly By Radiant Heating

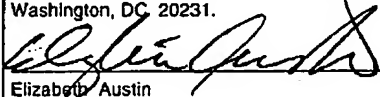

Docket Number: **TI-32508**
Art Unit: **2811**
Examiner: **TBD**
Conf. No.: **9018**

**RESPONSE TO REQUEST FOR SUBSTITUTE PAPERS**

October 21, 2002

Assistant Commissioner For Patents
Washington, D.C. 20231

Sir:

CERTIFICATION OF FACSIMILE TRANSMITTAL	
I hereby certify that on this date this correspondence is being facsimile transmitted to the Assistant Commissioner of Patents and Trademarks, Washington, DC 20231.	
 Elizabeth Austin	 Date 10/21/2002

Per your request, I am hereby faxing to you a copy of the following documents that were previously mailed to the USPTO on March 11, 2002. The returned post card from the USPTO, copy of the post card mailed on 03/11/02, Response to Notice to File Missing Parts of Application, Notice to File Missing Parts of Nonprovisional Application Request, Declaration and Power of Attorney, Assignment Recordation Sheet and Assignment, Letter to the Official Draftsperson, and Four Sheets of Formal Drawings.

Please let me know if I may be of further assistance.

Best regards,



Michael K. Skrehot
Attorney for Applicant
Reg. No. 36,682

Texas Instruments Incorporated
P. O. Box 655474, M/S 3999
Dallas, TX 75265
Ph: (972) 917-5653
Fx: (972) 917-4417



UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
www.uspto.gov

APPLICATION NUMBER	FILING/RECEIPT DATE	FIRST NAMED APPLICANT	ATTORNEY DOCKET NUMBER
10/032,907	12/28/2001	Jimmy Liang	TI-32508

23494
TEXAS INSTRUMENTS INCORPORATED
P O BOX 655474, M/S 3999
DALLAS, TX 75265

CONFIRMATION NO. 9018

FORMALITIES LETTER



OC000000007516333

Date Mailed: 02/22/2002

NOTICE TO FILE MISSING PARTS OF NONPROVISIONAL APPLICATION

FILED UNDER 37 CFR 1.53(b)

Filing Date Granted

An application number and filing date have been accorded to this application. The item(s) indicated below, however, are missing. Applicant is given **TWO MONTHS** from the date of this Notice within which to file all required items and pay any fees required below to avoid abandonment. Extensions of time may be obtained by filing a petition accompanied by the extension fee under the provisions of 37 CFR 1.136(a).

- The oath or declaration is unsigned.
- To avoid abandonment, a late filing fee or oath or declaration surcharge as set forth in 37 CFR 1.16(l) of \$130 for a non-small entity, must be submitted with the missing items identified in this letter.
- The balance due by applicant is \$ 130.

The application is informal since it does not comply with the regulations for the reason(s) indicated below.

The required item(s) identified below must be timely submitted to avoid abandonment:

- Substitute drawings in compliance with 37 CFR 1.84 because:
 - drawing sheets do not have the appropriate margin(s) (see 37 CFR 1.84(g)). Each sheet must include a top margin of at least 2.5 cm. (1 inch), a left side margin of at least 2.5 cm. (1 inch), a right side margin of at least 1.5 cm. (5/8 inch), and a bottom margin of at least 1.0 cm. (3/8 inch);
 - Drawings must be reasonably free from erasures and must be free from alterations, overwritings, interlineations, folds, and copy marks.
 - drawings have a line quality that is too light to be reproduced (weight of all lines and letters must be heavy enough to permit adequate reproduction) or text that is illegible (reference characters, sheet numbers, and view numbers must be plain and legible) see 37 CFR 1.84(l) and (p)(1);

*A copy of this notice **MUST** be returned with the reply.*

OCT-21-2002 15:32

TI

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M. Deput

Customer Service Center

Initial Patent Examination Division (703) 308-1202

PART 2 - COPY TO BE RETURNED WITH RESPONSE



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
Address: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231
www.uspto.gov

Application Number	Filing Date	First Named Applicant	Atty. Docket No.
10/032,907	12/28/2001	Liang, Jimmy	TI-32508

23494

TEXAS INSTRUMENTS INCORPORATED
P O BOX 655474, M/S 3999
DALLAS TX 75265

Title: Method and apparatus for flip chip device assembly by radiant heating

Date Mailed: 10/10/2002

Response 10/24/02

Request for Substitute Papers

The papers filed on 03/21/02 (certificate of mailing dated 03/11/02) are no longer in condition to become part of the permanent records of the United States Patent and Trademark Office (USPTO) for this application (37 CFR 1.52(a)) due to the United States Postal Service sanitization process.

The USPTO requests that applicant provide a copy of the above-identified papers (except for any U.S. or foreign patent documents submitted with the above-identified papers) with a statement that such copy is a complete and accurate copy of the above-identified papers (signing and returning a copy of this notice will provide such a statement). The reply to this letter should be submitted to the USPTO by facsimile at the number indicated **703-746-4060(OIPE)**.

Alternatively, the reply to this letter may be hand-carried to the Customer Service Window located in Room 1B03 of Crystal Plaza Building 2, Arlington, Virginia, 22202.

The USPTO strongly prefers that the reply to this letter be submitted by facsimile. However, if applicant cannot submit the reply to this letter by facsimile (or hand-delivery), the reply may be mailed to: Box Duplicate OIPE, U.S. Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202-2327.

This letter is not a notice under 37 CFR 1.251. However, failure to timely replay to this notice within **two (2) weeks** of the date of receipt of this letter may result in the USPTO issuing a notice under 37 CFR 1.251. A copy of this notice should be included with the reply.

The enclosed papers are a complete and accurate copy of the above-identified papers.

Name: Michael K. Skrehot Registration No.: 36,682Signature: [Signature] Date: 10/21/02

RECEIVED

OCT 15 2002

BEN KROGER



47/12-13-02
P3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Jimmy Liang, et al.

Art Unit: TBD

Serial No.: 10/032,907

Examiner: TBD

Filed: 12/28/01

Docket: TI-32508

For: Method and Apparatus for Flip Chip Device Assembly by Radiant Heating

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being deposited
with the U.S. Postal Service on 3-11-02
as First Class Mail in an envelope addressed to: Assistant
Commissioner for Patents, Washington, D.C. 20231.

Karen Vertz
Karen Vertz

3-11-02
Date

Assistant Commissioner for
Patents
Washington, D. C. 20231.

Dear Sir:

Enclosed are **FOUR (4)** sheets of formal drawings for the above-referenced case.
Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments
Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated
P.O. Box 655474 M/S 3999
Dallas, Texas 75265
(214) 939-8651

Respectfully submitted,

Gary C. Honeycutt
Gary C. Honeycutt
Reg. No. 20,250
Attorney for Applicants

10032907-102403